



Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1312-06**      Date: January 10, 2014  
Product Affected: TSSOP-56  
(Refer to Attachment II for the affected part numbers)

**MEANS OF DISTINGUISHING CHANGED DEVICES:**

- Product Mark      Lot # will have "A" prefix
- Back Mark
- Date Code
- Other

Date Effective: April 10, 2014

Contact: IDT PCN DESK  
E-mail: [pcndesk@idt.com](mailto:pcndesk@idt.com)

Attachment:       Yes       No

Samples: Please contact your local sales representative for sample request.

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

This notification is to advise our customers that IDT is adding OSE, Taiwan (OSET) as an alternate assembly facility for the selective devices of TSSOP-56.

There is no change to the moisture performance.

Attachment I details the qualification data for this change.  
Attachment II list the affected part numbers.

**RELIABILITY/QUALIFICATION SUMMARY:**

There is no expected change to the product quality and reliability.

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_  *Approval for shipments prior to effective date.*

Name/Date: \_\_\_\_\_ E-Mail Address: \_\_\_\_\_

Title: \_\_\_\_\_ Phone# /Fax# : \_\_\_\_\_

**CUSTOMER COMMENTS:**

\_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_ DATE \_\_\_\_\_



**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT I - PCN # : A1312-06**

**PCN Type:** Alternate Assembly Location

**Data Sheet Change:** None. No change in moisture sensitivity level (MSL).

**Detail Of Change:**

This notification is to advise our customers that IDT is adding OSE, Taiwan (OSET) as an alternate assembly facility for the selective devices of TSSOP-56.

The material sets used at OSE, Taiwan are qualified IDT materials.

There is no change to the moisture performance using the assembly material sets as listed in the below table.

Qualified Material Sets, by Assembly Subcontractor

Description	Existing	Add
Assembly Location	PT Unisem, Indonesia	OSE, Taiwan
Assembly Materials	Die Attach: CRM1076NS	Ablestik 8390
	Wire: Au Wire	Au Wire
	Mold Compound: G700LX	EME-G700L
	Lead Frame: Copper Alloy	Copper Alloy
	Plating: Matte 100% Sn	Matte 100% Sn

**Qualification Information and Qualification Data:**

**Qual Plan & Results:** The qualification was performed in accordance with JEDEC47 recommended tests

**Qual Vehicle:** TSSOP-56 (1 lot)

Test Description	Test Method	Test Results (SS / Rei)
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	45/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	77/0

Note:

\* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



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## **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

### **ATTACHMENT II - PCN # : A1312-06**

#### **Affected Part Numbers**

<b>Part Number</b>	<b>Part Number</b>	<b>Part Number</b>
74FCT16952ATPAG	74FCT16952CTPAG	74FCT16952ETPAG
74FCT16952ATPAG8	74FCT16952CTPAG8	74FCT16952ETPAG8